

Q NOTE	Revision	Date	Sheet
CC	1	8/20/13	1 of 1

Revisions:

Rev	Originator / Date	Revised / Date	Approval / Date:	Description:
1	RPS / 8/20/13		REH 8/28/13	Originated

SOLDERABILITY REQUIREMENTS IPC/EIA-J-STD-002

NOTE: This quality note applies to component parts only which are to be soldered at a higher level of assembly.

1. Components furnished under this Purchase Order shall be delivered with one of the approved termination finishes as listed below. The termination finish shall meet the solderability requirements of IPC/EIA-J-STD-002 (Category 3, Test Method A, B, or C, as applicable). A double tinning or dynamic solder wave process shall be used for any gold plating removal.

2. Approved Termination Finishes:
 - Tin-Lead (SnPb) with a minimum of 3% lead (Pb)
 - Palladium-silver (Pd/Ag)
 - Nickel palladium gold (Ni/Pd/Au) with less than 150 angstroms of gold
 - Gold (Au) on surface mount components in unformed flat packs and unformed quad packs
 - Gold (Au) on through-hole components/terminals with a gold thickness of less than 100 micro inches (2.5 um)

3. Specifically **DISALLOWED** finishes are all other finishes containing tin (Sn) with less than 3% lead (Pb) content, including pure tin (Sn), tin-bismuth (SnBi) and tin-silver-copper (SnAgCu).

4. **EXCEPTION:** If the Caton Connector Technical Data Package (Caton Connector Drawing or Military Specification) referenced on this order specifies the use of pure tin finishes this prohibition is **NOT** applicable.

<p>This document is an integral part of the contract (purchase order), which calls it out. The revision in effect at the time the purchase order was placed applies.</p>
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